

N-Channel Enhancement Mode Power MOSFET

General Description

The series of Power MOSFETs use advanced technology and design. This high voltage MOSFET fits Switched applications.

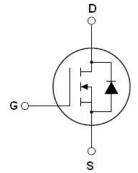
Features

- High speed switching
- Intrinsic capacitances and Qg minimized
- ●100% Avalanche Tested

Application

• Switched applications





Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE3N150T	TO-247	NCE3N150T



TO-247

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	Vds	1500	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	3	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	2.1	A
Pulsed drain current (Note 1)	I _{DM (pluse)}	9	A
Maximum Power Dissipation(Tc=25°C)	PD	187	W
Derate above 25°C		1.24	W/°C
Single pulse avalanche energy (Note 2)	Eas	225	mJ
Single pulse avalanche current (Note 2)	I _{AS}	3	A
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+175	C°

* limited by maximum junction temperature



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.8	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	50	°C /W

Table 3. Electrical Characteristics (TA=25 $^{\circ}$ Cunless otherwise noted)

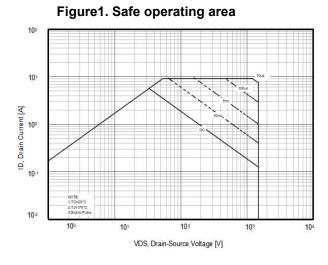
Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =1mA	1500			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =1500V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	IDSS	V _{DS} =1500V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	Igss	V _{GS} =±30V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3	4	5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =1.5A		5.5	7.5	Ω
Dynamic Characteristics				•		
Input Capacitance	Clss			1700		pF
Output Capacitance	Coss	V_{DS} =40V, V_{GS} =0V,		61		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		5.5		pF
Total Gate Charge	Qg			32		nC
Gate-Source Charge	Q _{gs}	V_{DS} =1200V,I _D =1.5A,		8.7		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		12		nC
Intrinsic gate resistance	R _G	f = 1 MHz open drain		2		Ω
Switching times				•		
Turn-on Delay Time	t _{d(on)}			22		nS
Turn-on Rise Time	tr	V_{DD} =750V, I_{D} =1.5A,		45		nS
Turn-Off Delay Time	t _{d(off)}	$R_G=3\Omega, V_{GS}=10V$		42		nS
Turn-Off Fall Time	t _f			58		nS
Source- Drain Diode Characteristics				•		
Source-drain current(Body Diode)	Isd	T OF O			3	А
Pulsed Source-drain current(Body Diode)	Isdm	T _c =25°C			9	А
Forward On Voltage	Vsd	Tj=25°C,I _{SD} =3A,V _{GS} =0V		0.8	1.1	V
Reverse Recovery Time	t _{rr}			390		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=3A,		2.2		uC
Peak Reverse Recovery Current	Irrm	di/dt=100A/µs		11		А

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)





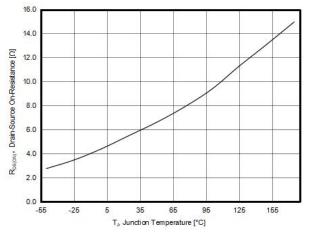


Figure 5. Maximum I_D vs Junction Temperature

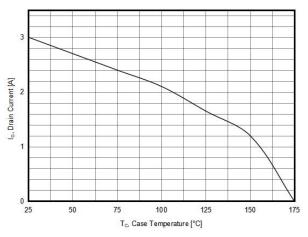


Figure2. Source-Drain Diode Forward Voltage

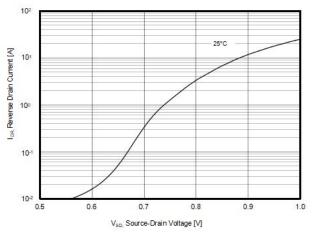


Figure4. BV_{DSS} vs Junction Temperature

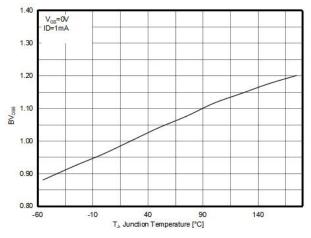


Figure6. Output characteristics

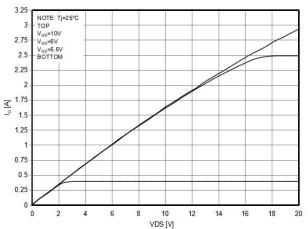
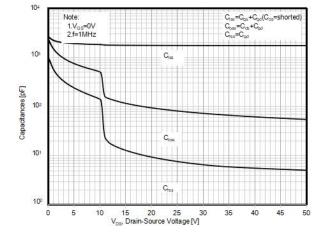
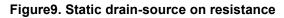


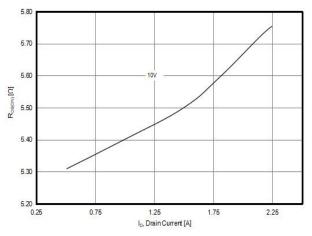


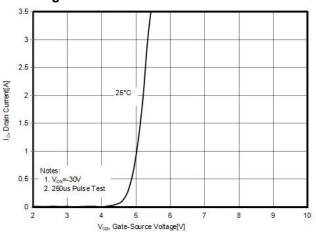
Figure7. Capacitance

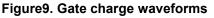


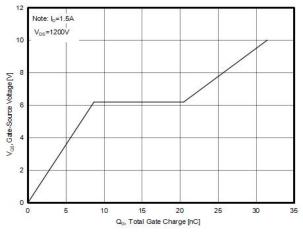








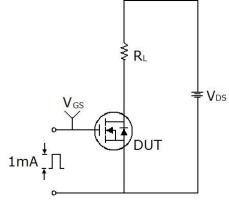


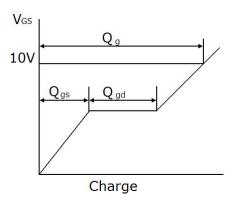




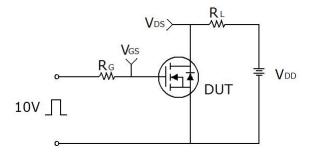
Test circuit

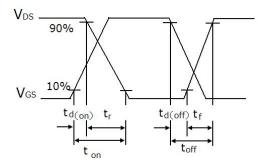
1) Gate charge test circuit & Waveform



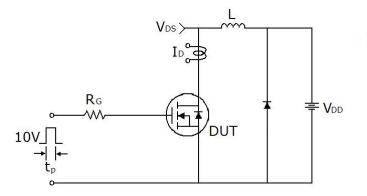


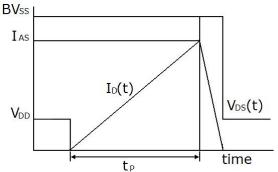
2) Switch Time Test Circuit:





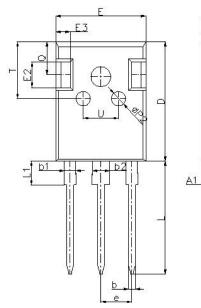
3) Unclamped Inductive Switching Test Circuit & Waveforms

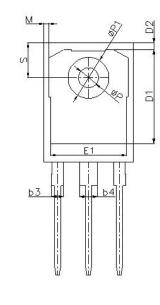






TO-247-E Package Information





O. makes l	Dimensions In Millimeters		Dimensions In Inches		
Symbol –	Min.	Max.	Min.	Max.	
A	4.90	5.10	0.193		
A1	2.31	2.51	0.091	0.099	
A2	1.90	2.10	0.075	0.083	
b	1.16	1.26	0.046	0.050	
b1	1.96	2.06	0.077	0.081	
b2	2.96	3.06	0.117	0.120	
b3	-	2.25	-	0.089	
b4	-	3.25	-	0.128	
С	0.59	0.66	0.023	0.026	
D	20.90	21.10	0.823	0.831	
D1	16.25	16.85	0.640	0.663	
D2	1.05	1.35	0.041	0.053	
E	15.70	15.90	0.618	0.626	
E1	13.10	13.50	0.516	0.531	
E2	4.40	4.60	0.173	0.181	
E3	2.40	2.60	0.094	0.102	
e	5.436	BSC	0.214B	SC	
L	19.80	20.10	0.780	0.791	
L1	-	4.30	-	0.169	
M	0.35	0.95	0.014	0.037	
Q	5.60	6.00 0.220		0.236	
S	6.05	6.25	0.238	0.246	
Т	9.80	10.20	0.386	0.402	
U	6.00	6.40	0.236	0.252	

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